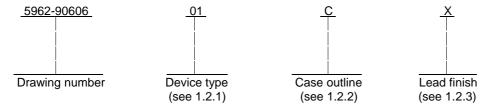
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DSCC FORM 2233 APR 97

R 97 5962-E274-00 DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

## 1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.
  - 1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function
01	54F113	Dual J-K negative edge-triggered flip-flop with set input
02	54F112	Dual J-K negative edge-triggered flip-flop with set and reset inputs

1.2.2 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Descriptive designator</u>	<u>Terminals</u>	Package style
Descriptive designator	<u>Terminals</u>	Package style
GDIP1-T14 or CDIP2-T14	14	Dual in-line
GDFP1-F14 or CDFP2-F14	14	Flat pack
GDIP1-T16 or CDIP2-T16	16	Dual in-line
GDFP2-F16 or CDFP3-F16	16	Flat pack
CQCC1-N20	20	Square chip carrier
	Descriptive designator  GDIP1-T14 or CDIP2-T14 GDFP1-F14 or CDFP2-F14 GDIP1-T16 or CDIP2-T16 GDFP2-F16 or CDFP3-F16	Descriptive designator Terminals  GDIP1-T14 or CDIP2-T14 14 GDFP1-F14 or CDFP2-F14 14 GDIP1-T16 or CDIP2-T16 16 GDFP2-F16 or CDFP3-F16 16

- 1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.
- 1.3 Absolute maximum ratings. 1/

Supply voltage range Input voltage range Input current range Voltage applied to output in high output state range Current applied to output in low output state	-0.5 V dc minimum to +7.0 V dc maximum -0.5 V dc minimum to +7.0 V dc maximum -30.0 mA to +5.0 mA -0.5 V to $V_{CC}$
Storage temperature range	-65°C to +150°C
Thermal resistance, junction-to-case (Θ <sub>JC</sub> )	See MIL-STD-1835
Junction temperature (T <sub>J</sub> )	+175°C
Lead temperature (soldering, 10 seconds)	+300°C
Maximum power dissipation ( $P_D$ ) $\underline{2}$ /	
Device type 01	115.5 mW
Device type 02	104.5 mW

Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

<sup>2/</sup> Maximum power dissipation is defined as V<sub>CC</sub> x I<sub>CC</sub> and must withstand the added P<sub>D</sub> due to the short-circuit output test.

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## 1.4 Recommended operating conditions.

Supply voltage ( $V_{CC}$ )	+4.5 V minimum to +5.5 V dc maximum 2.0 V dc 0.8 V dc -18 mA -1.0 mA 20 mA -55°C to +125°C
Minimum setup time, $J_n$ or $K_n$ to $\overline{\mathrm{CP}}\! n$ , high $(t_s(H))$	
$T_C = +25^{\circ}C$	4.0 ns
Device type 01	6.0 ns
Device type 02	5.0 ns
Minimum setup time, $J_n$ or $K_n$ to $\overline{CPn}$ , low $(t_s(L))$	
T <sub>C</sub> = +25°C	3.5 ns
$T_{C} = -55^{\circ}C, +125^{\circ}C$	
Device type 01	5.0 ns
Device type 02	4.0 ns
Minimum hold time, $J_n$ or $K_n$ to $CPn$ ,	
high or low $(t_h(H))$ , $t_h(L)$ )	0.0 ns
Minimum $\overline{\text{CPn}}$ pulse width, high or low $(t_W(H), t_W(L))$	
$T_{C} = +25^{\circ}C$	4.5 ns
$T_C = -55^{\circ}C$ , +125°C	5.0 ns
Minimum $\overline{SDn}$ or $\overline{RDn}$ pulse width, low $(t_w(L))$	
$T_C = +25^{\circ}C$	4.5 ns
$T_C = -55^{\circ}C, +125^{\circ}C$	5.0 ns
Minimum recovery time, $\overline{SDn}$ or $\overline{RDn}$ to $\overline{CPn}$ , $(t_{rec})$	
$T_C = +25^{\circ}C$	
Device type 01	4.5 ns
Device type 02	4.0 ns
$T_C = -55^{\circ}C$ , +125°C	6.0 no
Device type 01  Device type 02	6.0 ns 5.0 ns
Device type 02	0.0 113

# 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

# **SPECIFICATION**

# DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

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#### **STANDARDS**

#### **DEPARTMENT OF DEFENSE**

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-973 - Configuration Management.
MIL-STD-1835 - Interface Standard For Microcircuit Case Outlines.

#### **HANDBOOKS**

#### **DEPARTMENT OF DEFENSE**

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

#### 3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used. This drawing has been modified to allow the manufacturer to use the alternate die/fabrication requirements of paragraph A.3.2.2 of MIL-PRF-38535 or other alternative approved by the Qualifying Activity.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
  - 3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.4 herein.
  - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.3 Truth tables. The truth tables shall be as specified on figure 2.
  - 3.2.4 Logic diagrams. The logic diagrams shall be as specified on figure 3.
  - 3.2.5 Test circuit and switching waveforms. The test circuit and switching waveforms shall be as specified on figure 4.
- 3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.
- 3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 Marking. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein). For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.

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- 3.5.1 <u>Certification/compliance mark.</u> For product built in accordance with A.3.2.2 of MIL-PRF-38535, or as modified in the manufacturer's Quality Management (QM) Plan, the "QD" certification mark shall be used in place of the "QML" or "Q" certification mark.
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DSCC-VA shall be required in accordance with MIL-PRF-38535, appendix A.
- 3.9 <u>Verification and review</u>. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq \text{T}_{\text{C}} \leq +125^{\circ}\text{C}$ unless otherwise specified		Group A subgroups	Device type	Liı	mits	Unit
						Min	Max	
High level output voltage	V <sub>OH</sub>	$V_{CC} = 4.5 \text{ V}$	$I_{OH} = -1.0 \text{ mA}$	1, 2, 3	All	2.5		
		$V_{IL} = 0.8 V,$	$V_{IH} = 2.0 \ V$					
Low level output voltage	V <sub>OL</sub>	$V_{CC} = 4.5 \text{ V}$	$I_{OL} = 20 \text{ mA}$	1, 2, 3	All		0.5	V
		$V_{IL} = 0.8 V$ ,	$V_{IH} = 2.0 \ V$					
Input clamp voltage	V <sub>IK</sub>	$V_{CC} = 4.5 \text{ V},$	$I_{IN} = -18 \text{ mA}$	1, 2, 3	All		-1.2	
High level input current	I <sub>IH1</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>IN</sub> = 2.7 V	1, 2, 3	All		20	μΑ
	I <sub>IH2</sub>	$V_{CC} = 5.5 \text{ V},$	$V_{IN} = 7.0 \text{ V}$	1, 2, 3	All		100	
			J <sub>n</sub> , K <sub>n</sub>				-0.6	
Low level input current	I <sub>IL</sub>	$V_{CC} = 5.5 \text{ V}$	<u></u>	1, 2, 3	All		-3.0	mA
		$V_{IN} = 0.5 \text{ V}$	SDn , RDn					
			CPn				-2.4	
Short circuit output current	Ios	$V_{CC} = 5.5 \text{ V},$	V <sub>OUT</sub> = 0.0 V	1, 2, 3	All	-60	-150	
<u>1/</u>								
Supply current	Icc	$V_{CC} = 5.5 \text{ V}$		1, 2, 3	01		21	mA
<u>2</u> /					02		19	
Functional tests		See 4.4.1c	V <sub>CC</sub> = 4.5 V, 5.5 V	7, 8	All			
		$R_L = 500 \Omega$	V <sub>CC</sub> = 5.0 V	9	01	85		
Maximum clock frequency	f <sub>MAX</sub>	$C_L = 50 pF$	V <sub>CC</sub> = 4.5 V, 5.5 V	10, 11		80		MHz
<u>3</u> /		See figure 4	V <sub>CC</sub> = 5.0 V	9	02	90		
			V <sub>CC</sub> = 4.5 V, 5.5 V	10, 11	1	90		1

See footnotes at end of table

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TABLE I. <u>Electrical performance characteristics</u>. Continued

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq \text{T}_{\text{C}} \leq +125^{\circ}\text{C}$ unless otherwise specified		Group A subgroups	Device type	Lir	nits	Unit
						Min	Max	
		$R_L = 500 \Omega$	$V_{CC} = 5.0 \text{ V}$	9	01	2.0	6.0	
Propagation delay time,	t <sub>PLH1</sub> ,	$C_L = 50 pF$	$V_{CC} = 4.5 \text{ V}, 5.5 \text{ V}$	10, 11		2.0	8.0	
$\overline{\text{CP}}$ n to Q <sub>0</sub> , $\overline{\text{Q}}$ n	t <sub>PHL1</sub>		V <sub>CC</sub> = 5.0 V	9	02	2.0	6.5	ns
		See figure 4	V <sub>CC</sub> = 4.5 V, 5.5 V	10, 11		2.0	7.5	
			V <sub>CC</sub> = 5.0 V	9	01	2.0	6.5	1
Propagation delay time,	t <sub>PLH2</sub> ,		V <sub>CC</sub> = 4.5 V, 5.5 V	10, 11		2.0	8.5	
$\overline{SDn}$ or $\overline{RDn}$ to $Q_n$ , $\overline{Qn}$	t <sub>PHL2</sub>		V <sub>CC</sub> = 5.0 V	9	02	2.0	6.5	1
			V <sub>CC</sub> = 4.5 V, 5.5 V	10, 11		2.0	7.5	

- 1/ Not more than one output should be shorted at a time, and the duration of the short-circuit condition should not exceed one second.
- $\underline{2}$ / With clock input grounded and all outputs open,  $I_{CC}$  is measured with Q and  $\overline{Q}$  outputs high in turn.
- 3/ For subgroups 10 and 11,  $f_{MAX}$ , if not tested, shall be guaranteed to the specified limits.

Device types	01		02		
Case outlines	C and D	2	E and F	2	
Terminal number	Termi symb		Terminal s	ymbol	
1	CP1	NC	CP1	NC	
2	K1	CP1	K1	CP1	
3	J1	K1	J1	K1	
4	SD1	J1	SD1	J1	
5	Q1	NC	Q1	SD1	
6	$\overline{Q}1$	SD1	$\overline{Q}1$	NC	
7	GND	NC	$\overline{Q}_2$	Q1	
8	$\overline{Q}_2$	Q1	GND	-Q1	
9	Q2	-Q1	Q2	$\overline{Q}_2$	
10	SD2	GND	SD2	GND	

Device types	01		02	
Case outlines	C and D	2	E and F	2
Terminal number	Terminal symbol		Terminal symbol	
11	J2	NC	J2	NC
12	K2	$\overline{Q}2$	K2	Q2
13	CP2	Q2	CP2	SD2
14	V <sub>CC</sub>	SD2	RD2	J2
15		NC	RD1	K2
16		J2	Vcc	NC
17		NC		CP2
18		K2		$\overline{RD}2$
19		CP2		RD1
20		Vcc		Vcc

NC = No connection

FIGURE 1. Terminal connections.

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# Device type 01

Operating made	Inputs				Outputs	
Operating mode	SDn	CPn	Jn	Kn	Qn	- Qn
Asynchronous set	L	Χ	Χ	Χ	Н	L
Toggle	Н	$\downarrow$	h	h	- q	q
Load "0" (reset)	Н	$\downarrow$	1	h	L	Н
Load "1" (set)	Н	$\downarrow$	h	1	Н	L
Hold "no change"	Н	$\downarrow$	1	1	q	$\overline{\mathbf{q}}$

# Device type 02

Operating made		Inputs					Outputs	
Operating mode	SDn	RDn	CPn	Jn	Kn	Qn	Qn	
Asynchronous set	L	Н	Х	Х	X	Н	L	
Asynchronous reset (clear)	Н	L	X	X	X	L	Н	
Undetermined	L	L	Х	Х	Х	Н	Н	
Toggle	Н	Н	<b>↓</b>	h	h	$\overline{q}$	q	
Load "0" (reset)	Н	Н	$\downarrow$	1	h	L	Н	
Load "1" (set)	Н	Н	$\downarrow$	h	- 1	Н	L	
Hold "no change"	Н	Н	↓	I	I	q	- q	

H = High voltage level steady state L = Low voltage level steady state

h = High voltage level one setup time prior to the high-to-low clock transition

I = Low voltage level one setup time prior to the high-to-low clock transition

q = State of the referenced output one setup time prior to the high-to-low clock transition

X = Immaterial

↓ = High-to-low clock transition

# FIGURE 2. Truth tables.

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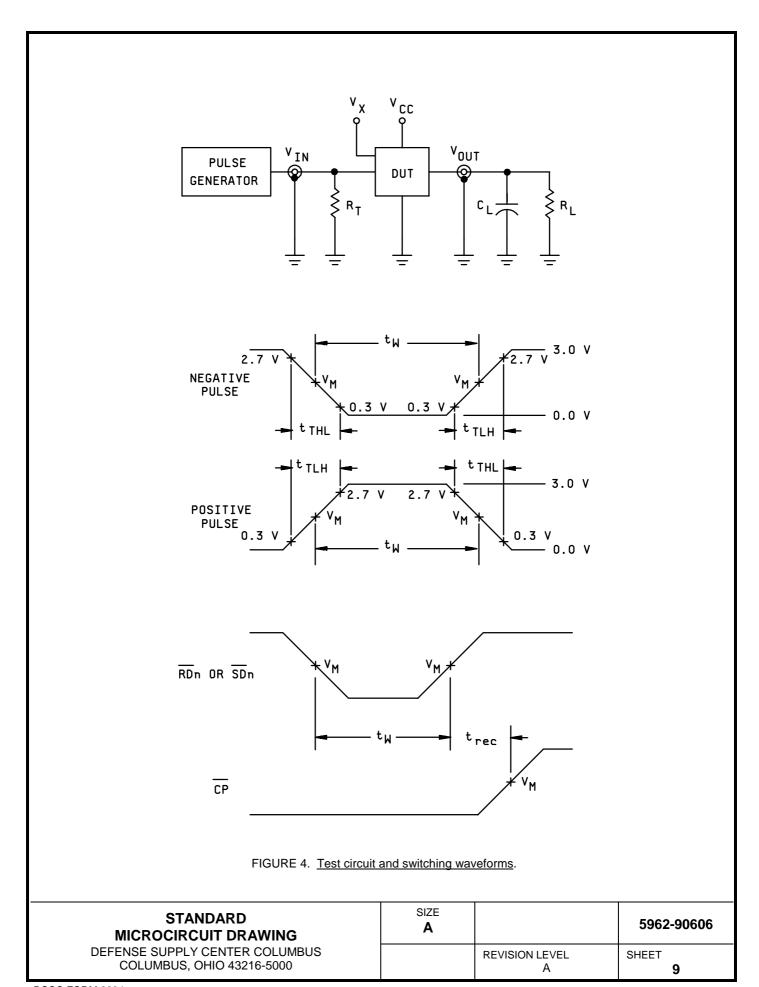
# Device type 01 (1/2 shown) ā SD . ĸ٠ CP Device type 02 (1/2 shown) Q-Q SD RD СP FIGURE 3. Logic diagrams. SIZE **STANDARD** 5962-90606 Α **MICROCIRCUIT DRAWING**

**REVISION LEVEL** 

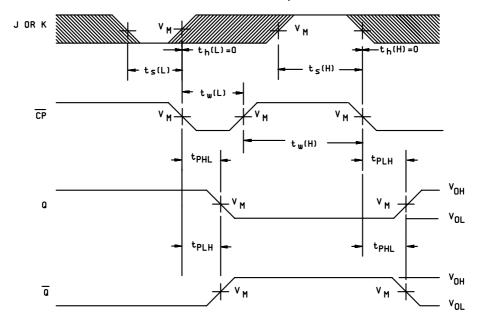
SHEET

8

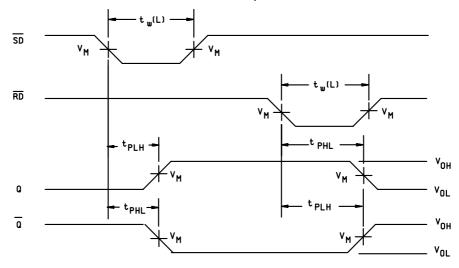
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000



Clock to output delay times, data setup and hold times, and clock pulse width



Set or reset to ouput delay times and set and reset pulse widths



## NOTES:

- 1. For all waveforms,  $V_M = 1.5 \text{ V}$ .
- 2.  $C_L = Load$  capacitance includes jig and probe capacitance.
- 3.  $R_T$  = Termination resistance should be equal to  $Z_{OUT}$  of pulse generator.
- 4.  $V_X$  = Unclocked pins must be held at  $\leq 0.8 \ V_1 \geq 2.7 \ V$  or open.
- 5. All input pulses must have the following characteristics: PRR = 1 MHz,  $t_{TLH} = t_{THL} \le 2.5$  ns,  $t_W = 500$  ns, duty cycle = 50 percent.

FIGURE 4. <u>Test circuit and switching waveforms</u> - Continued.

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## 4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9, 10, 11
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

<sup>\*</sup> PDA applies to subgroup 1.

- 4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
    - c. Subgroups 7 and 8 shall include verification of the truth table.

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## 4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
  - (1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
  - (2)  $T_A = +125^{\circ}C$ , minimum.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

#### 5. PACKAGING

- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0525.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0674.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD		
MICROCIRCUIT DRAWING		
DEFENSE SLIPPLY CENTER COLLIMBI		

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## STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 00-05-24

Approved sources of supply for SMD 5962-90606 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-9060601CA	<u>3</u> /	
5962-9060601DA	<u>3</u> /	
5962-90606012A	<u>3</u> /	
5962-9060602EA	<u>3</u> / 0C7V7	54F112/BEA 54F112/EA
5962-9060602FA	<u>3</u> / 0C7V7	54F112/BFA 54F112/FA
5962-90606022A	<u>3</u> / 0C7V7	54F112/B2A 54F112/2A

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source.

Vendor CAGEVendor namenumberand address

0C7V7 QP Labs

3605 Kifer Road Santa Clara, CA 95051

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.